

JIS

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JIS C 6492 : 1998

**Base materials for printed circuits—
Bismaleimide/triazine modified
epoxide woven glass fabric
copper-clad laminated sheet
of defined flammability
(vertical burning test)**

ICS 31.180

Descriptors : printed-circuit bases, laminates, copper, glass, epoxides

Reference number : JIS C 6492 : 1998 (E)

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Foreword

This translation has been made based on the original Japanese Industrial Standard revised by the Minister of International Trade and Industry through deliberations at Japanese Industrial Standards Committee in accordance with the Industrial Standardization Law. Consequently **JIS C 6492 : 1993** is replaced with **JIS C 6492 : 1998**.

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In the event of any doubts arising as to the contents,
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**Base materials for printed circuits—
Bismaleimide/triazine modified epoxide
woven glass fabric copper-clad
laminated sheet of defined flammability
(vertical burning test)**

Introduction This Japanese Industrial Standard has been prepared based on IEC 60249-2-18 *Base materials for printed circuits—Part 2 : Specifications—Specification No.18 : Bismaleimide/triazine modified epoxide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test)* published as the first edition in 1992, Amendment 1 (1993) and Amendment 2 (1994) with some modifications in line with actual conditions in Japan to such items as surface corrosion, corrosion at the edge, etc. Those amendments were edited and compiled into the text.

The portions with dotted underlines show the matters not included in the original International Standard. The IEC standard number is based on the new numbering system of IEC standards put in force on January 1st, 1997, and the standards published before the said date are numbered by adding 60000 to the former number. This is only the change in the numbering system and the contents remain unchanged.

1 Scope This Standard specifies requirements on bismaleimide/triazine modified epoxide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test), in thickness of 0.5 mm up to 6.4 mm (hereafter referred to as “copper-clad laminates”).

Remarks 1 To designate this material, the reference 60249·2·18·FV1·IEC·BTE·GC·Cu may be used; if there is no risk of confusion, the type designation may be abbreviated to read IEC·60249·2·18·FV1.

2 The corresponding International Standard is as follows.

IEC 60249-2-18 : 1992 *Base materials for printed circuits—Part 2 : Specifications—Specification No.18 : Bismaleimide/triazine modified epoxide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test)*

2 Normative references The following standards contain provisions which, through reference in this Standard, constitute provisions of this Standard. The most recent editions of the standards indicated below shall be applied.

JIS C 6481 *Test methods of copper-clad laminates for printed wiring boards*

JIS C 6515 *Copper foil for printed wiring boards*

Remarks : This standard is identical with IEC 61249-5-1 : 1995 *Materials for interconnection structures—Part 5 : Sectional specification set for conductive foils and films with and without coatings—Section 1 : Copper foils (for the manufacture of copper-clad base materials)*.

IEC 60249-1 : 1982 *Base materials for printed circuits—Part 1 : Test methods. Amendment No. 4 (1993)*